	Hits	Search Text	DBs
47	22	((heat$4 or anneal$7 or bak$4 or cur$4 or post$5heat$4 or thermal$4 or solidifying or solidification or solidify) same (pattern or mask or stencil$3 or frame) same (trench$4 or hole or opening or via) same (liquid or solution) same (material or solute or compound or substance) same (atomiz$6 or deposit$4 or coat$4) same (organometallic or (conductive near12 organic)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
48	13	((heat$4 or anneal$7 or bak$4 or cur$4 or post$5heat$4 or thermal$4 or solidifying or solidification or solidify) same (pattern or mask or stencil$3) same (trench$4 or hole or opening or via or through$4hole) same (liquid or solution) same (material or solute or compound or substance pr precursor) same (atomiz$6 or deposit$4 or spray$5coat$4 or spin$4coat$4) same (organometallic or (conductive near12 organic)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
49	21	((pattern or mask or stencil$3 or frame) same (trench$4 or hole or opening or via) same (liquid or solution) same (material or solute or compound or substance) same (atomiz$6 or deposit$4 or coat$4) same (organometallic or (conductive near12 organic))) and ((heat$4 or anneal$7 or bak$4 or cur$4 or post$5heat$4 or thermal$4 or solidification or solidify) same (precursor or liquid or solution) same (conductive or metal$4 or organometallic) same (evaporat$4 or anneal$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
50	75	((pattern or mask or stencil$3) same (trench$4 or hole or opening or via or through$4hole) same (liquid or solution or precursor) same (atomiz$6 or deposit$4 or coat$4 or fill$4) same (organometallic or (conductive near12 organic) or (metal$4 near7 organic))) and ((heat$4 or anneal$7 or bak$4 or cur$4 or post$5heat$4 or thermal$4 or solidifying or solidification or solidify) same (precursor or liquid or solution) same (conductive or metal$4 or organometallic) same (evaporat$4 or anneal$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
51	21	((pattern or mask or stencil$3 or frame) same (trench$4 or hole or opening or via) same (liquid or solution) same (material or solute or compound or substance) same (atomiz$6 or deposit$4 or coat$4) same (organometallic or (conductive near12 organic))) and ((heat$4 or anneal$7 or bak$4 or cur$4 or post$5heat$4 or thermal$4 or solidification or solidify) same (precursor or liquid or solution) same (conductive or metal$4 or organometallic) same (evaporat$4 or anneal$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
52	54	S63 NOT S64	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
53	19	((pattern or mask or stencil$3) same (trench$4 or hole or opening or via or through$4hole) same (liquid or solution or precursor) same (print$4) same (organometallic or (conductive near12 organic) or (metal$4 near7 organic))) and ((heat$4 or anneal$7 or bak$4 or cur$4 or post$5heat$4 or thermal$4 or solidifying or solidification or solidify) same (precursor or liquid or solution) same (conductive or metal$4 or organometallic) same (evaporat$4 or anneal$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB